

Features

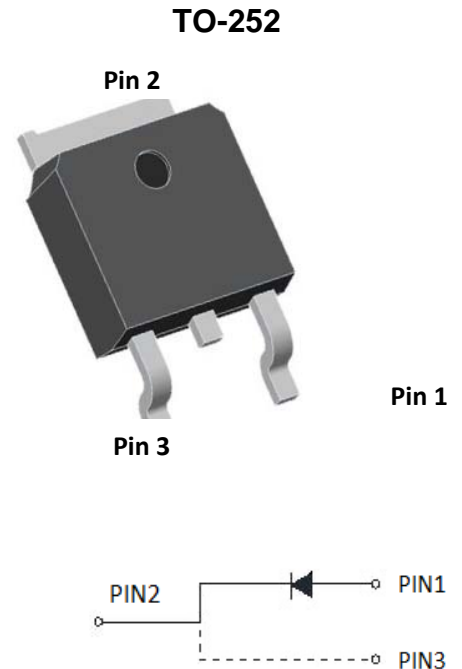
- Adopt FRED chip
- Low forward Voltage drop
- Fast reverse recovery time
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability

Typical Applications

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-252
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked



■Maximum Ratings (T_j=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	MUR860DS
Device marking code			MUR860DS
Repetitive Peak Reverse Voltage	V _{RRM}	V	600
Average Rectified Output Current @60Hz sine wave, R-load, T _c (FIG.1)	I _O	A	8
Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, T _j =25°C	I _{FSM}	A	80
Current Squared Time @1ms≤t≤8.3ms T _j =25°C ,	I ² t	A ² s	41
Storage Temperature	T _{stg}	°C	-55 ~ +150
Junction Temperature	T _j	°C	-55 ~ +150
Junction capacitance @4V,1MHz	C _j	pF	40



■ Electrical Characteristics

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max	
Instantaneous forward voltage drop per diode	V_{FM}	V	$I_{FM}=8.0A @T_j=25^{\circ}C$	-	1.45	1.65	
			$I_{FM}=8.0A @T_j=150^{\circ}C$	-	1.25	1.35	
DC reverse current at rated DC blocking voltage per diode	I_{RRM1}	uA	$V_{RM}=V_{RRM}$ $T_j=25^{\circ}C$	-	-	5.0	
	I_{RRM2}		$V_{RM}=V_{RRM}$ $T_j=150^{\circ}C$	-	40	200	
Reverse Recovery Time	T_{RR}	ns	$I_F=0.5A$ $I_{RM}=1A$ $I_{RR}=0.25A$ $T_j=25^{\circ}C$	-	25	35	
			$T_j=25^{\circ}C$	-	60	-	
			$T_j=125^{\circ}C$	-	300	-	
Peak recovery current	I_{RRM}	A	$T_j=25^{\circ}C$	$I_F=8A$ $di/dt=-200A/us$ $V_{RM}=200V$	-	3.4	-
			$T_j=125^{\circ}C$		-	6.4	-
Reverse recovery charge	Qrr	nC	$T_j=25^{\circ}C$		-	100	-
			$T_j=125^{\circ}C$		-	300	-

■ Thermal Characteristics ($T_j=25^{\circ}C$ Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	MUR860DS
Thermal Resistance	Between junction and case	$R_{\theta J-C}$	$^{\circ}C/W$	5.0
	Between junction and Air	$R_{\theta J-A}$	$^{\circ}C/W$	50

■ Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MUR860DS	Approximate 0.31	2500	2500	25000	Reel

■ Characteristics (Typical)

FIG1: I_o - T_c Curve

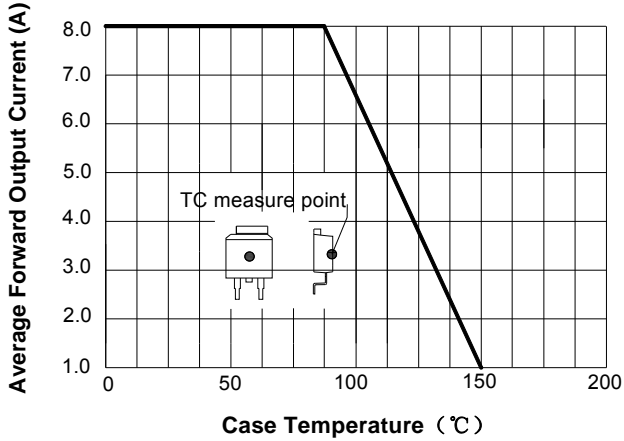


FIG2: Surge Forward Current Capability

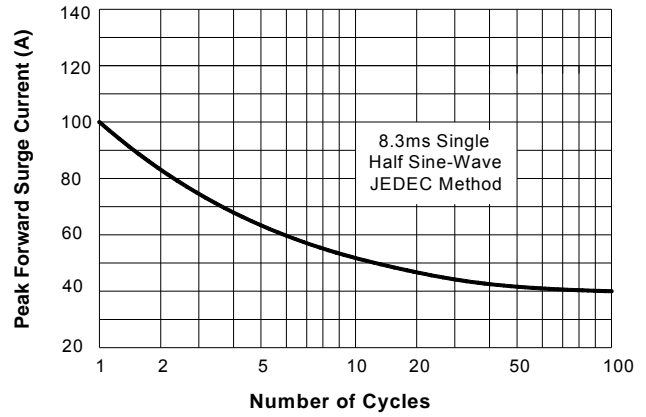


FIG3: Forward Voltage

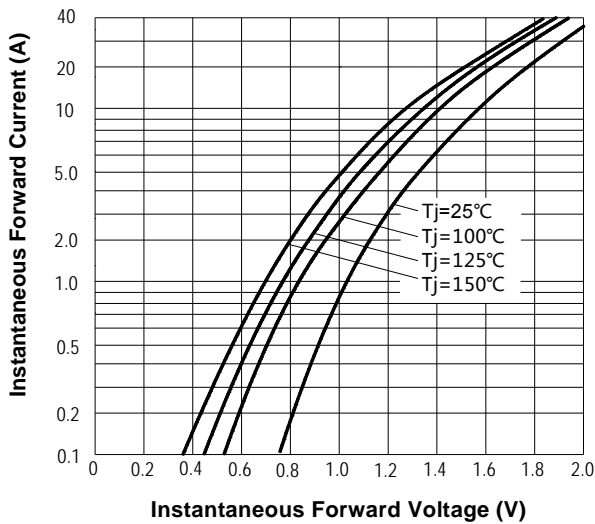


FIG4: Instantaneous Reverse Characteristics

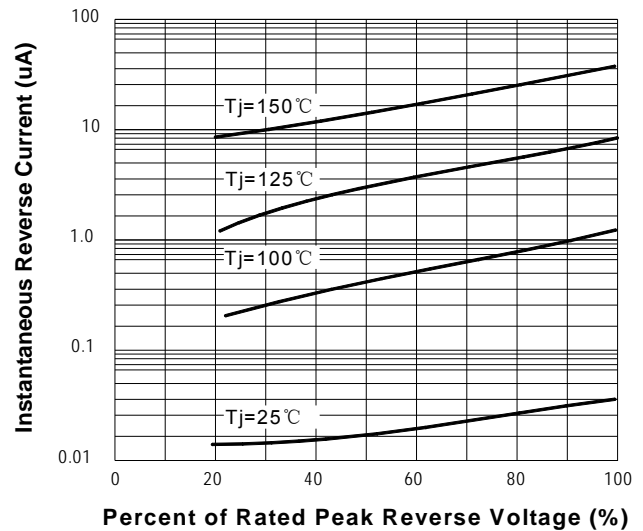
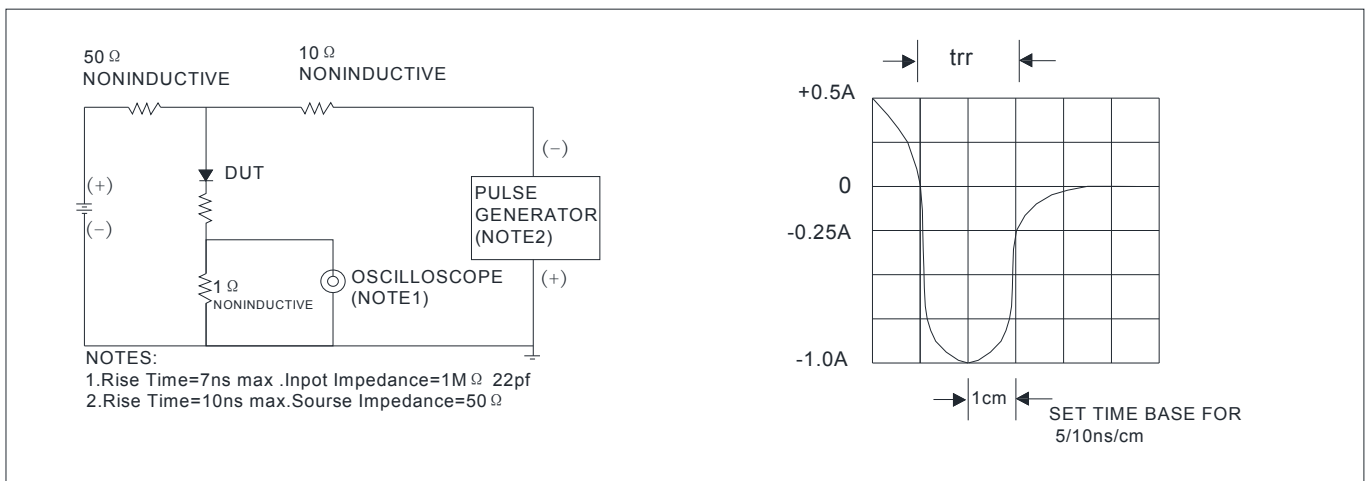
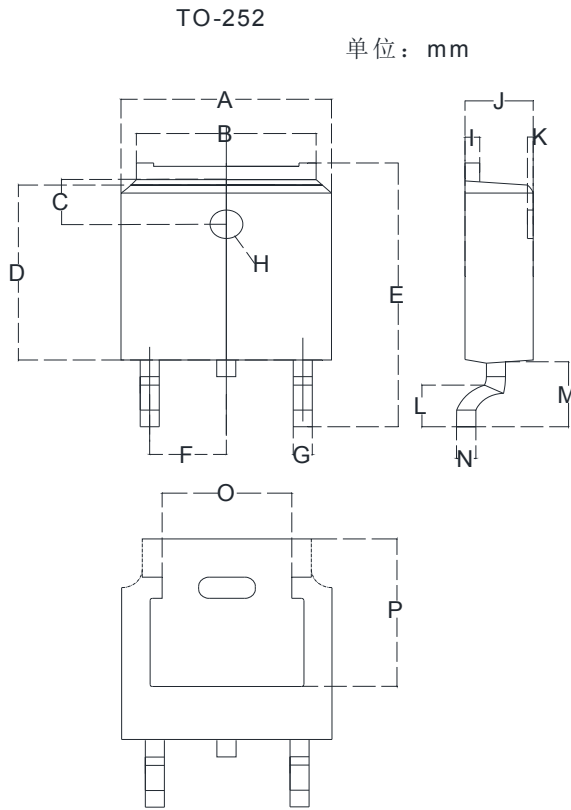


FIG5: Diagram of circuit and Testing wave form of reverse recovery time

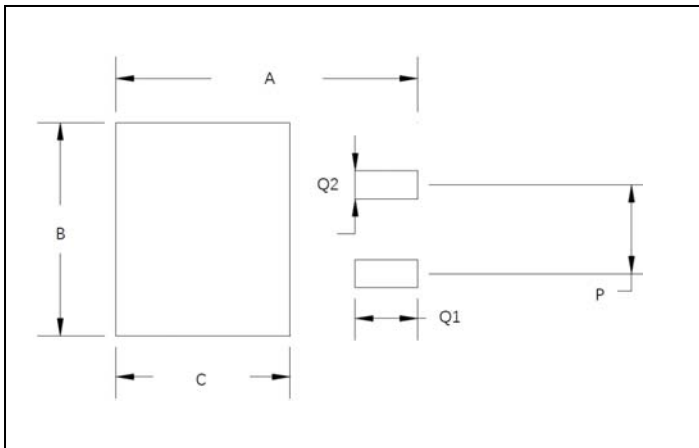


■Outline Dimensions



TO-252		
Dim	Min	Max
A	6.500	6.700
B	5.100	5.460
C	1.400	1.800
D	6.000	6.200
E	10.000	10.400
F	2.166	2.366
G	0.660	0.860
H	Φ 1.050	Φ 1.350
I	0.460	0.580
J	2.200	2.400
K	0	0.300
L	0.890	2.290
M	2.730	3.080
N	0.430	0.580
O	4.20	4.95
P	5.15	5.45

■Suggested Pad Layout



Dim	Millimeters
A	11.4
B	6.74
C	6.23
P	4.56
Q1	2.28
Q2	1.52

Packge	Packing	Box Size L×W×H(mm)	Quantity(pcs/box)	Carton Size L×W×H(mm)	Quantity(pcs/carton)
TO-252	80pcs/Tube	560×150×50	4000	570×290×180	40000
TO-252	2500pcs/Reel	335×335×40	2500	370×370×440	12500/25000